

GARY C. HONEYCUTT
Direct Dial: 214.939.8651
ghoneycutt@godwingruben.com

Attorneys
A Professional Corporation

Renaissance Tower
1201 Elm Street, Suite 1700
Dallas, Texas 75270
214.939.4400
214.760.7332 Fax

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Commissioner of Patents
and Trademarks
Washington, D.C. 20231

Re: Patent Application for:
"Fixture and Method for Uniform Electroless Metal Deposition on Integrated
Circuit Bond Pads"
Serial No.: 09/817,694
Attorney Docket: TI-30592
Our File: 50000.2126

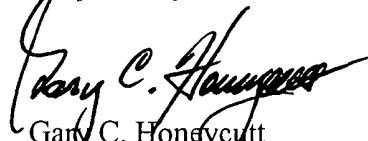
Dear Sir:

Enclosed for filing please find the following items relating to the above-identified application:

- (1) Election Document; and
- (2) Postcards.

Please file the above documents and return the date-stamped postcards to the corresponding addresses, as indicated. In the meantime, if you have any questions or comments concerning this matter, please call the undersigned. Otherwise, please accept the enclosed.

Respectfully submitted,


Gary C. Honeycutt
Reg. No. 20,250

GCH:glc
Enclosures
cc: James Brady, III (Texas Instruments, w/ encls.)

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